



**KEEP BEST
PCBA**

DFM Report

Product Name:	K23002A0
Prepared By:	Panfeng Qin
Report Rev:	V1.0
Date:	2024-1-11
Page:	10

Table of Contents

<u>Summary</u>	1
<u>PCBA Image Overview(3D)</u>	3
<u>Package analysis(Assembly)</u>	4
<u>Ass ComponentLayout</u>	6
<u>Ass LandPattern(IPC7351B)</u>	7
<u>Components Information Summary</u>	8
<u>BOM Verification Report</u>	9
<u>No Library List</u>	10

DFM Report

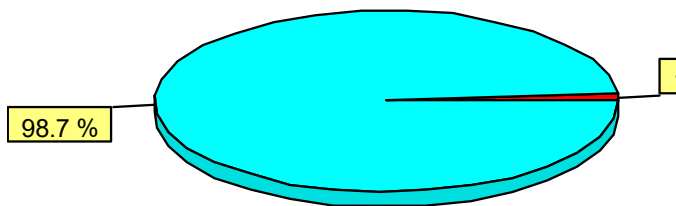
Generated by VayoPro-DFM Expert, Format v3.0

Basic Information

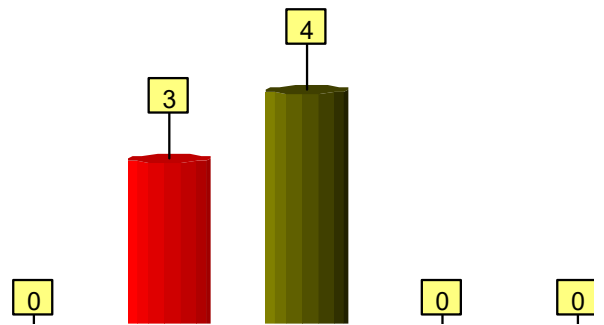
Customer Name:	Size L x W(mm)
CAD File: Pick Place for JI A M	Thickness(mm): 1.600
BOM File: K23002A0 JI A M H.758765.007-04	20230407.xlsx
Matched Component (PN): 96.67%	Single or double reflow: Null
Matched Component (RefDes): 99.47%	Through hole parts on 1 or both sides: Null

Summary of review results

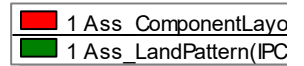
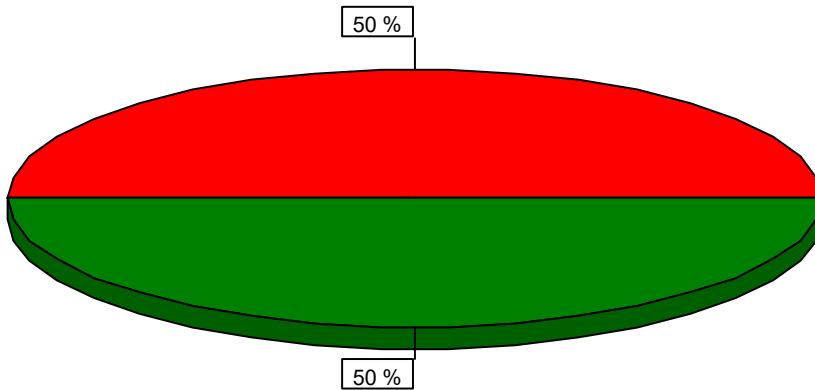
Analysis Summary



Priority Summary



Risk Category Summary

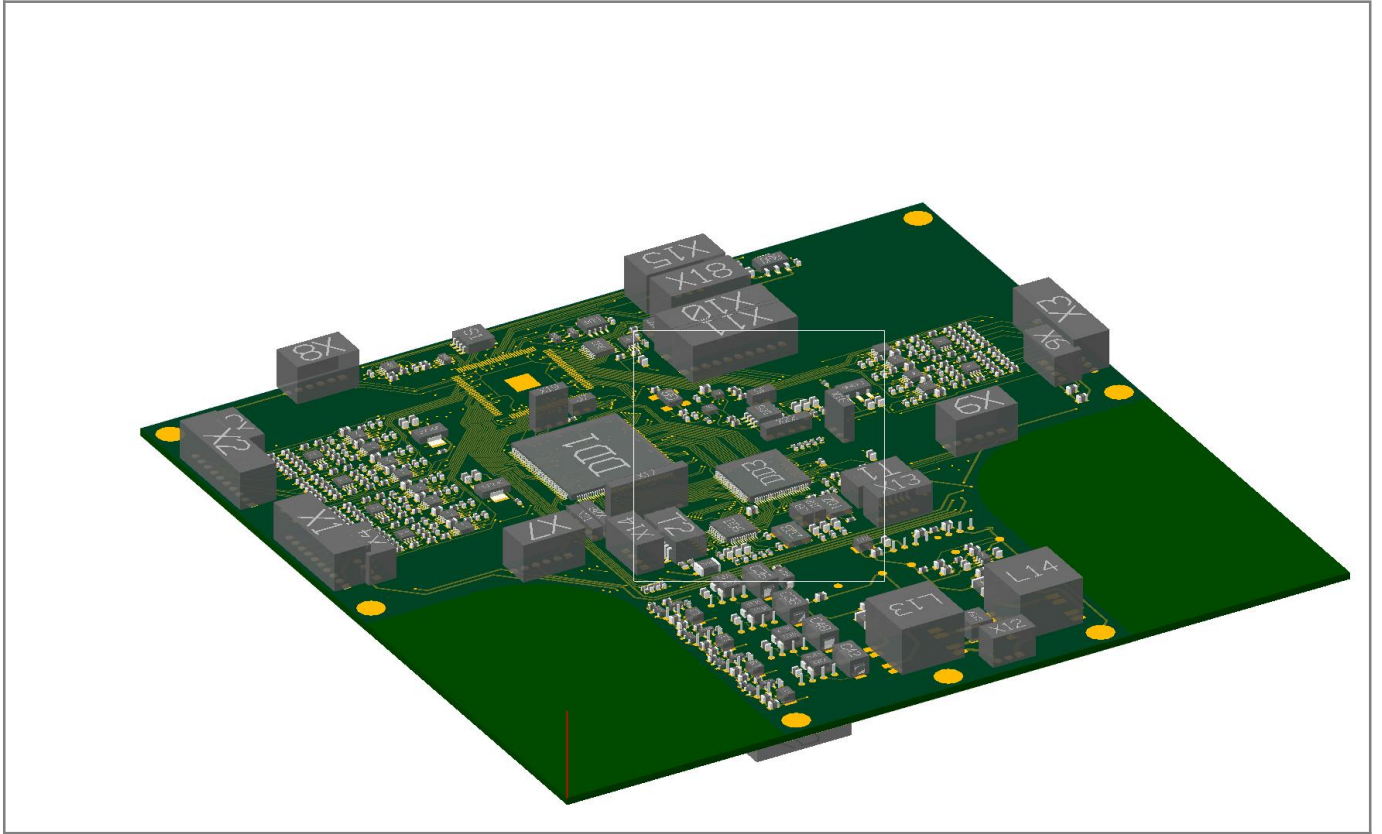


Summary of review items

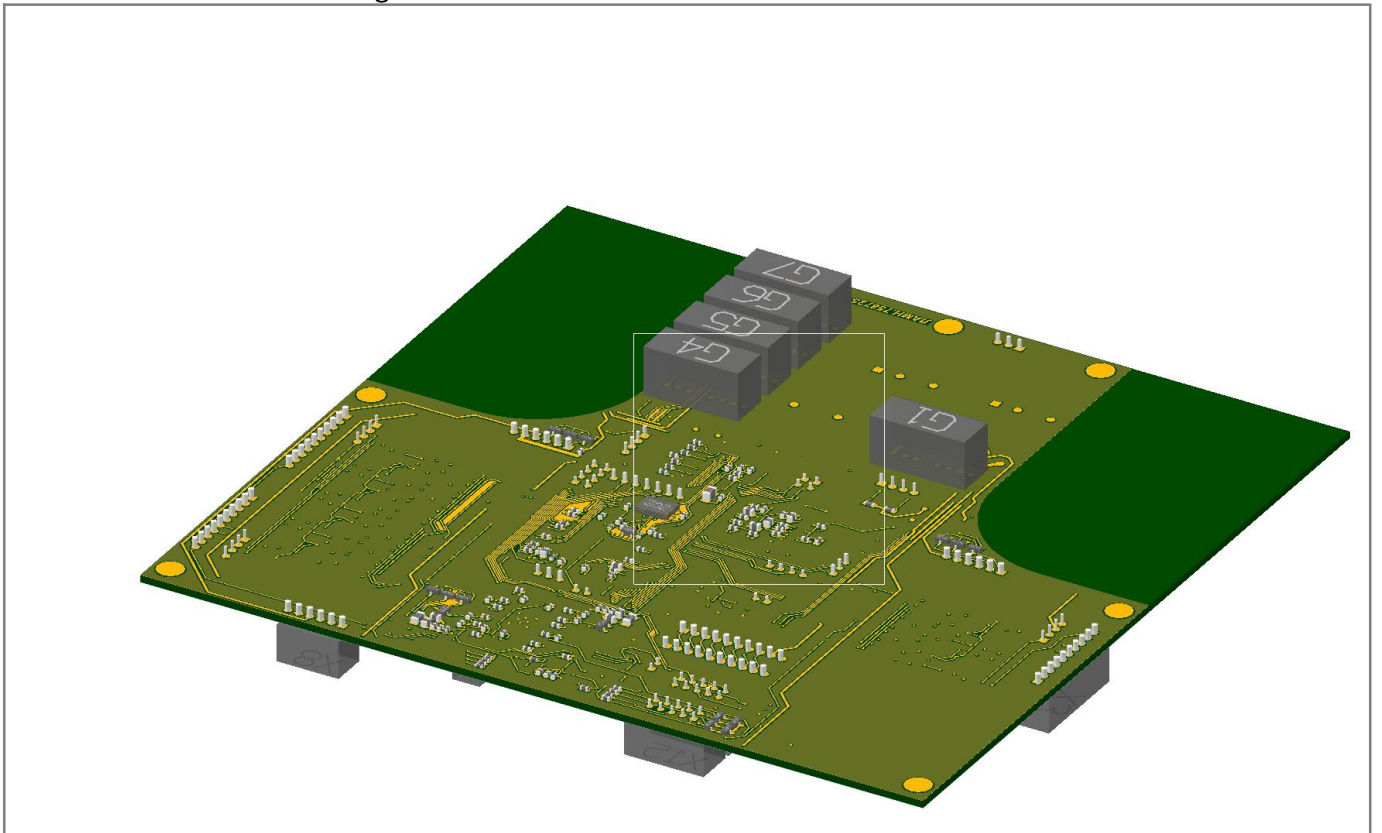
#	Analysis category	Item	Defects	Conclusion
1	Ass_ComponentLayout	83	1	FAIL
2	Ass_General	183	0	PASS
3	Ass_LandPattern(IPC7351B)	6	1	FAIL
4	Ass_LandPattern(IPC782)	3	0	PASS
5	Ass_LandPattern(TH)	19	0	PASS
6	Ass_Other	10	0	PASS
7	Ass_Routing	36	0	PASS
8	Ass_SolderPaste	12	0	PASS
9	Ass_StencilPaste	61	0	PASS
10	Ass_Wave	19	0	PASS
11	Fab_Silkscreen	20	0	PASS
12	TestPoint	11	0	PASS

PCBA Overview(3D)

Overview of Top Image



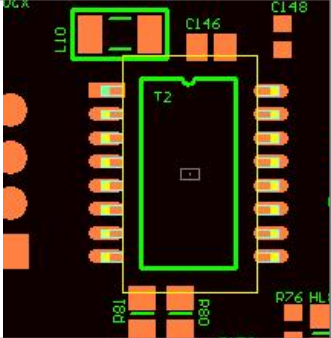
Overview of Bottom Image



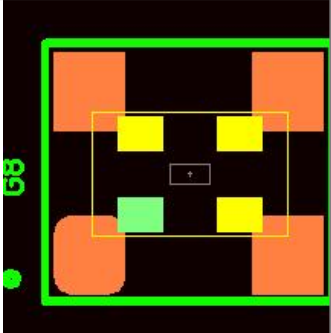
Report Items

Package analysis(Assembly)

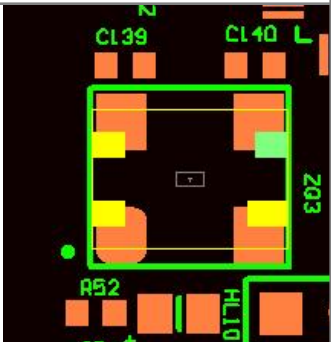
1) 30-00-0073

POTENTIAL RISK/RECOMMENDATION				GRAPHICAL DESCRIPTION		RECOMMENDED DESIGN
#	Location1	Location2	Std Value	Act Value (mm)	Image Captured	Comment
1	P/N: 30-00-007 3 CAD Shape: N2-16	N2-16 68.7654 76.0509				30-00-0073 T1, T2 components are too large and cover other components

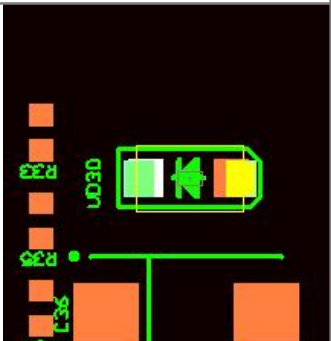
2) 19-00-0774

POTENTIAL RISK/RECOMMENDATION				GRAPHICAL DESCRIPTION		RECOMMENDED DESIGN
#	Location1	Location2	Std Value	Act Value (mm)	Image Captured	Comment
1	P/N: 19-00-077 4 CAD Shape: KX0-V97	KX0-V97 96.9000 126.8999				19-00-0774 G8 components are too small

3) 19-00-0772

POTENTIAL RISK/RECOMMENDATION				GRAPHICAL DESCRIPTION	RECOMMENDED DESIGN	
#	Location1	Location2	Std Value	Act Value (mm)	Image Captured	Comment
1	P/N: 19-00-077 2 CAD Shape: KX0-V97	KX0-V97 90.5838 67.5858				19-00-0772 ZQ1 ZQ3 components do not match the pads

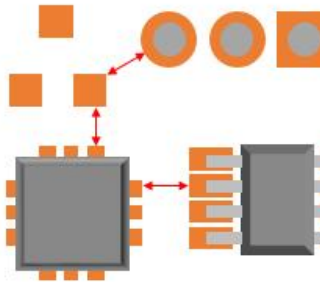
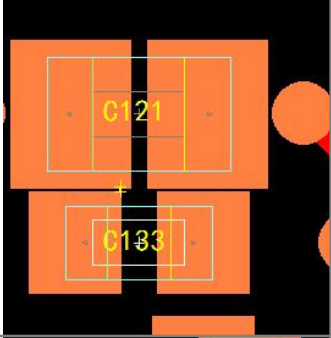
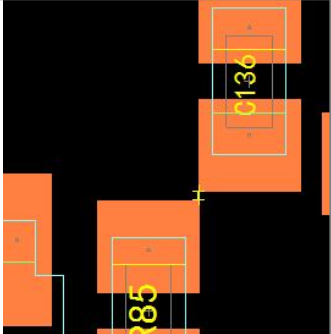
4) 15-00-3036

POTENTIAL RISK/RECOMMENDATION				GRAPHICAL DESCRIPTION	RECOMMENDED DESIGN	
#	Location1	Location2	Std Value	Act Value (mm)	Image Captured	Comment
1	P/N: 15-00-303 6 CAD Shape: sma	sma 80.2000 52.4998				15-00-3036 VD1, VD16, VD17, VD19, VD20, VD21, VD22, VD23, VD30 components are too large

Ass_ComponentLayout

1) DFX-1042-1

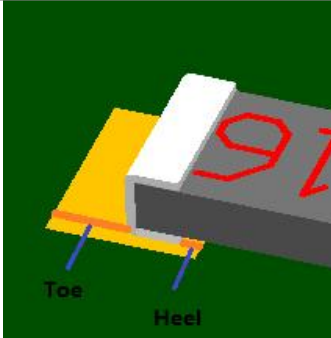
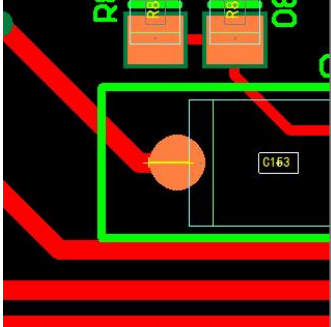
Pad distances of different components

POTENTIAL RISK/RECOMMENDATION				GRAPHICAL DESCRIPTION	RECOMMENDED DESIGN	
<p>The pads of different components are too close, which affects production yield and maintenance.</p>						
#	Location1	Location2	Std Value	Act Value (mm)	Image Captured	Comment
1	Bottom Pads C133.1 80.7856 121.2344	Bottom Pads C121.1 80.7856 121.1876	=>8mil (0.2mm)	0.0468mm		C133,C121 is too close to the pad
2	Bottom Pads R85.2 79.1356 105.6844	Bottom Pads C136.1 79.1356 105.5876	=>8mil (0.2mm)	0.0968mm		R85,C136 is too close to the pad

Ass_LandPattern(IPC7351B)

1) DFX-1328-3

大于或等于 1608 (0603) 的矩形或方形端子趾部焊盘尺寸

POTENTIAL RISK/RECOMMENDATION				GRAPHICAL DESCRIPTION		RECOMMENDED DESIGN
<p>元件引脚前端焊盘尺寸未满足 IPC-7351 焊盘设计规范要求。</p>						
#	Location1	Location2	Std Value	Act Value (mm)	Image Captured	Comment
1	Top Component C153.1 67.1499 64.5000	Top Pads Same value pin:C153.2 66.1584 64.5000	0.15~0.55 mm (6~22mil)	0.9915mm		C153, C110 component patch pad plug-in

Appendix1: Parts Information Summary

PN Information

TOP QTY (SMD)	69
Bottom QTY (SMD)	0
Total QTY (SMD)	0
TOP QTY (PTH)	0
Bottom QTY (PTH)	0
Total QTY (PTH)	0

Part Information

TOP QTY (SMD)	408
Bottom QTY (SMD)	0
Total QTY (SMD)	408
TOP QTY (PTH)	0
Bottom QTY (PTH)	0
Total QTY (PTH)	0

Appendix2: BOM Verification Report

BOM Verification Report

BOM & CAD Verification Report

Mismatch parts (in BOM not in CAD)

RefDes	PN	Description
PCB	10-K23002H41	JI A M H. 758765.007-04

Unloaded parts (in CAD not in BOM)

J1	MH1	MH2	MH3	MH4	MH5	MH6	MH7
----	-----	-----	-----	-----	-----	-----	-----

Appendix3: No Library List

Note: The device in the following list does not use the real component library.

No Library List

#	PN	Description	MPN	Manufacture
---	----	-------------	-----	-------------

No Library RefDes List

#	RefDes	PN	Package
---	--------	----	---------